

ICPT 2026

October 19-22, 2026

Science and Technology Convention Center,
Seoul, South Korea

October 21 (Wed.), 2026

[Oral 08] CMP Consumables (I)

15:10-16:35

International Conference Hall (B1F)

● Session Chair: Xinping Qu (Fudan Univ., China)

15:10-15:35 **[Invited]** Advanced Ceria Slurries for SiO₂ CMP: Polishing Mechanism of
[Oral 08-1] Nanoceria and Emerging Applications

Hisataka Minami (Resonac Corp., Japan)

15:35-15:55
★[Oral 08-2] W CMP Oxidants for Ultra-low Chemical Dissolution with High Removal Rate

Yearin Byun, Thanh Cuong Nguyen, Inkwon Kim, Nohjun Park, Doyoon Kim,
Yeonah Jeong, Heechul Moon, and Sangkyun Kim (Samsung Electronics Co.,
Ltd., Korea)

15:55-16:15 Advanced Soft Pad Conditioning Solutions for Improved Pad Life and
[Oral 08-3] Defectivity in Cu Barrier Applications

Uma Rames Krishna Lagudu, Chikai Chiu, Prasoon Gupta, Jiadi Fan (3M, USA),
Holden Lee, Chung I Ho, Jason Lin, Yuhsun Wang (3M, Taiwan), Changwan
Bea, Yoonghee Na (3M, Korea), Inki Kim (3M, USA), Benson Chen (3M,
Taiwan), and Yongsuk Yang (3M, Korea)

16:15-16:35
[Oral 08-4] CMP Process and Slurries for Memory Device Stacking

Yuchun Wang (Anji Microelectronics, China)